

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-7. (cancelled)

8. (previously presented) A mold for making a heat curable composite material part, comprising:

a liquid coating of a stripping composition on the mold, wherein,

the stripping composition is solvent-free and is polymerized by heating, and

the stripping composition comprises:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

- 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;

- 5 to 10 parts by weight of an anti-adhesion modulator constituted by an epoxy polydimethylsiloxane which is not polymerized and

- an anti-stick agent making the composition less tacky prior to polymerization, which comprises 8 to 12 parts by weight dodecyl monovinyl ether in the stripping composition and 8 to 12

parts by weight of cyclohexane dimethanol divinyl ether in the stripping composition.

9-12. (cancelled)

13. (previously presented) The mold according to claim 8, wherein

the polymerization agent is 5 to 7 parts by weight;
and

said anti-adhesion modulator is an epoxy polydimethylsiloxane.

14. (previously presented) The mold according to claim 13, wherein

- the polymerization agent is 6 parts by weight;
- the anti-adhesion modulate is 8 parts by weight; and
- the dodecyl monovinyl ether is present at a concentration of 11.4 parts by weight, and
- the cyclohexane dimethanol divinyl ether is present at a concentration of 11.4 parts by weight.

15. (previously presented) A wipe or cloth impregnated in the stripping composition of claim 8.

16. (previously presented) A method of molding a heat curable composite material part, comprising:

forming a composite material in a mold coated by a liquid stripping composition, wherein,

the surface of the mold is coated with the stripping composition to a thickness of about one micrometer,

the stripping composition is solvent-free and is polymerized by heating, and

the stripping composition comprises:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

- 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;

- 5 to 10 parts by weight of an anti-adhesion modulator constituted by an epoxy polydimethylsiloxane which is not polymerized; and

- an anti-stick agent making the composition less tacky prior to polymerization, which comprises 8 to 12 parts by weight dodecyl monovinyl ether in said stripping composition and 8 to 12 parts by weight of cyclohexane dimethanol divinyl ether in said stripping composition.

17-23. (cancelled)

24. (previously presented) The method according to claim 16, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.

25-26. (cancelled)

27. (previously presented) The method according to claim 16, wherein the polymerization cycle is 1 hour at $150^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

28. (previously presented) The method according to claim 16, wherein the polymerization cycle is 30 minutes at 100°C .

29-30. (cancelled)

31. (previously presented) The method according to claim 16, wherein the composite material part formed in the mold is a helicopter blade or an element of such a blade.

32-33. (cancelled)

34. (withdrawn) A stripping composition to be applied as a coating on a mold for making a heat curable composite material part, comprising:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

- 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;

- 5 to 10 parts by weight of an anti-adhesion modulator constituted by an epoxy polydimethylsiloxane which is not polymerized; and

- an anti-stick agent making the composition less tacky prior to polymerization, which comprises 8 to 12 parts by weight dodecyl monovinyl ether in the stripping composition and 8 to 12 parts by weight of cyclohexane dimethanol divinyl ether in the stripping composition,

wherein the stripping composition is a solvent-free liquid that is polymerized by heating.